L Number	Hits	Search Text	DB	Time stamp
1	373	glass adj1 (substrate or board) and (vias or (through adj1 holes)) and (filler or sealant)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:47
3	29	361/760 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:48
4	16	361/748 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
5	14	361/736 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
6	10	361/750 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
7	9	361/751 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
8	11	361/761 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
9	3	361/765 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
10	13	361/767 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:49
11	2	361/768 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:50
12	14	174/250 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:50
13	22	174/255 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:51

C:\APPS\east\workspaces\09671436 Display device with glass substrate.wsp

14	26	174/262 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:51
15	12	174/263 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:51
16	31	174/260 and (glass adj1 (substrate or board)) and (vias or (through adj1 holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:51
2	48	(glass adj1 (substrate or board)) and (vias or (through near holes)) and filler and (display adj1 device)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/07/14 14:51